

超软导热垫片

Thermal Pad Ultra Soft Series

产品介绍

PRODUCT INTRODUCTION

超软导热垫片具有超低硬度，高压缩性等特点，相对于常规导热垫片具有超低的安装应力，可避免安装应力对芯片或者线路板的破坏。适合对于安装应力要求高和公差较大的场合。

Ultra soft thermal pad has the characteristics of ultra-low hardness and high compressibility. Compared with common thermal pad, it has ultra-low installation stress which can avoid the damage of installation stress to chip or circuit board. It is suitable for occasions with low compression stress and large tolerance.

产品特点

PRODUCT FEATURE

- 高压缩性，低安装应力
- 更高的接触热阻
- 适应更大的公差场合
- High compressibility, low installation stress
- Lower contact thermal resistance
- Adapt to larger tolerance scenario

典型应用

TYPICAL APPLICATION

- 汽车电子
- Automotive electronics
- 家电
- Household electrical appliances
- 可穿戴设备
- Wearable devices
- 装配应力敏感芯片
- Stress sensitive chip
- 公差较大环境
- Environment with large tolerance

产品参数

PRODUCT PARAMETER

产品型号 Product Name	厚度 Thickness	导热系数 Thermal Conductivity	密度 Density	硬度 Hardness	介电常数 Dielectric Constant	体积电阻率 Volume Resistivity	使用温度 Application Temperature	阻燃等级 Flammability Rating	保质期 Shelf Life
	mm	W/m.K	g/cm ³	Shore 00	@1MHz	Ω·cm	℃	UL-94	month
STP 200 S	0.5~5.0	2.1	2.44	40	3.6	1.0*10 ¹³	-40 ~ 150	V-0	24
STP 300 S	0.5~10.0	3	2.80	40	5.2	1.0*10 ¹²	-40 ~ 150	V-0	24
STP 500 S	0.5~10.0	5	3.30	45	6.4	1.0*10 ¹³	-40 ~ 150	V-0	24
STP 800 S	0.5~5.0	8	3.50	40	4.5	5.9*10 ¹²	-40 ~ 150	V-0	24